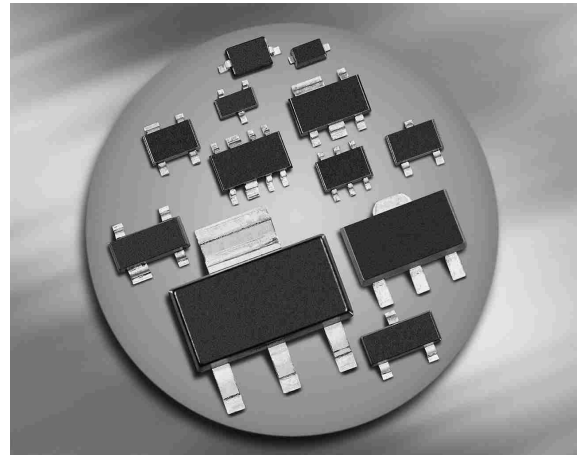


RF ESD Protection Diodes

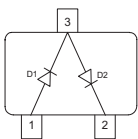
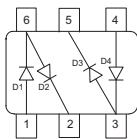
- ESD / transient protection of RF antenna / interfaces or ultra high speed data lines acc. to:
IEC61000-4-2 (ESD): ± 20 kV (contact)
IEC61000-4-4 (EFT): 40 A (5/50 ns)
IEC61000-4-5 (surge): 10 A (8/20 μ s)
- Ultra low capacitance of 1 pF typ.
(0.5 pF per diode)
- Low clamping voltage
- Pb-free (ROHS compliant) package
- Qualified according AEC Q101


Applications in anti-parallel configuration

- For low RF signal levels without superimposed DC voltage: e.g. GPS, WLAN, Bluetooth

Applications in rail-to-rail configuration

- For high RF signal levels or low RF signal levels with superimposed DC voltage: e.g. HDMI, S-ATA, Gbit Ethernet


ESD1P0RFW

ESD1P0RFS


Type	Package	Configuration	Marking
ESD1P0RFS	SOT363	2 channels	E6s
ESD1P0RFW	SOT323	1 channel	E6s

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge ¹⁾	V_{ESD}	20	kV
Peak pulse current ($t_p = 8 / 20 \mu\text{s}$) ²⁾	I_{pp}	10	A
Operating temperature range	T_{op}	-55...150	°C
Storage temperature	T_{stg}	-65...150	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Reverse working voltage ³⁾	V_{RWM}	-	-	70	V
Reverse current $V_R = 70 \text{ V}$	I_R	-	-	100	nA
Forward clamping voltage ²⁾ $I_{\text{pp}} = 3 \text{ A}, t_p = 8/20 \mu\text{s}$ $I_{\text{pp}} = 10 \text{ A}, t_p = 8/20 \mu\text{s}$	V_{FC}	-	4 12	7 15	V
Line capacitance ⁴⁾ $V_R = 0 \text{ V}, f = 1 \text{ MHz}$ $V_R = 0 \text{ V}, f = 1 \text{ MHz}$, for Application example 4	C_T	-	1 0.5	1.5 0.75	pF
Series inductance (per diode) SOT323 SOT363	L_S	-	1.4 1.6	- -	nH

¹⁾ V_{ESD} according to IEC61000-4-2, only valid in anti-parallel or rail-to-rail connection.

Please refer to the application examples.

²⁾ I_{pp} according to IEC61000-4-5, only valid in anti-parallel or rail-to-rail connection.

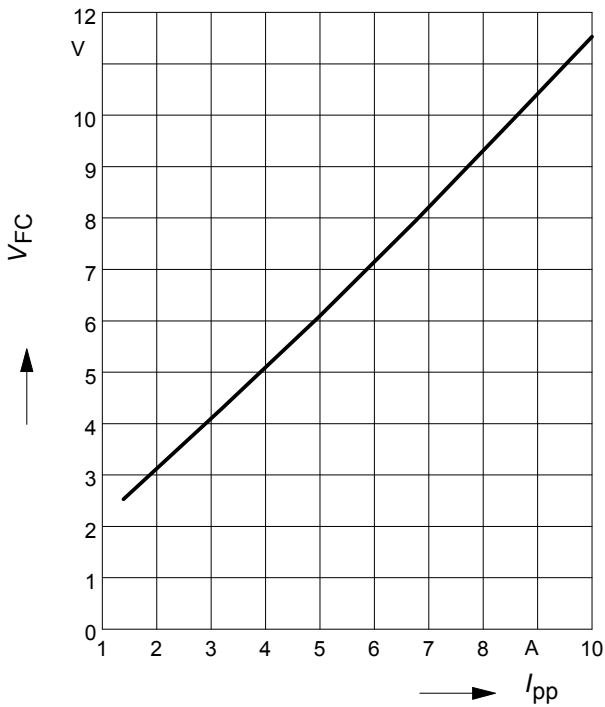
Please refer to the application examples.

³⁾Only valid in rail-to-rail configuration $V_{\text{CC}} \geq V_{\text{RWM}}$

⁴⁾Total capacitance line to ground (2 diodes in parallel)

Forward clamping voltage $V_{FC} = f(I_{PP})$

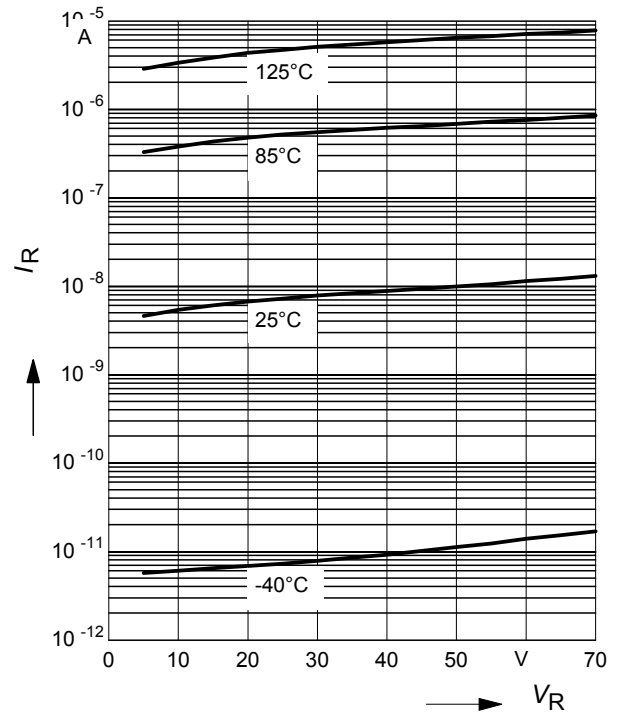
$t_p = 8 / 20 \mu s$



Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$

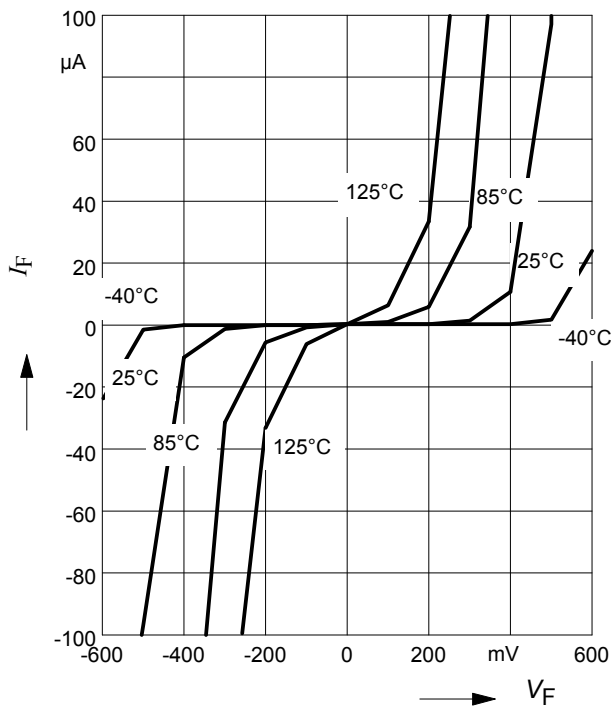
in rail-to-rail configuration



Forward current $I_F = f(V_F)$

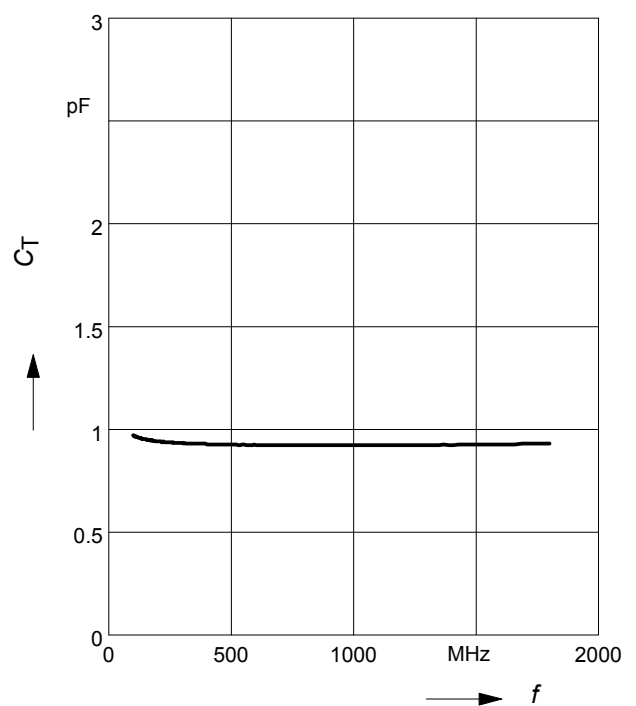
$T_A = \text{Parameter}$

in anti-parallel configuration



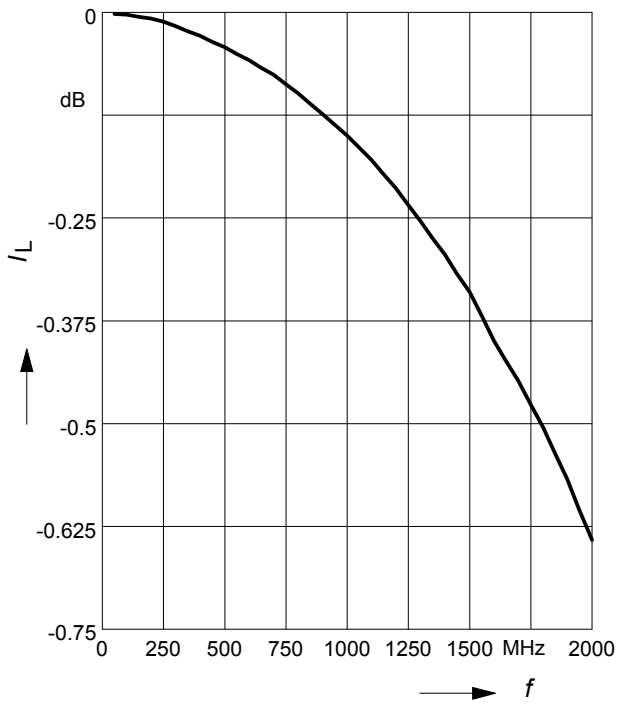
Line capacitance $C_T = f(f)$

$V_R = 0 V$



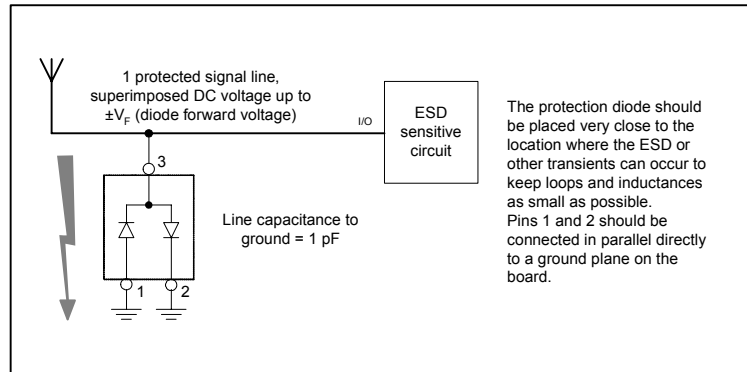
Insertion loss $|S_{21}|^2 = f(f)$

$V_R = 0$ V, line to ground, $Z = 50 \Omega$



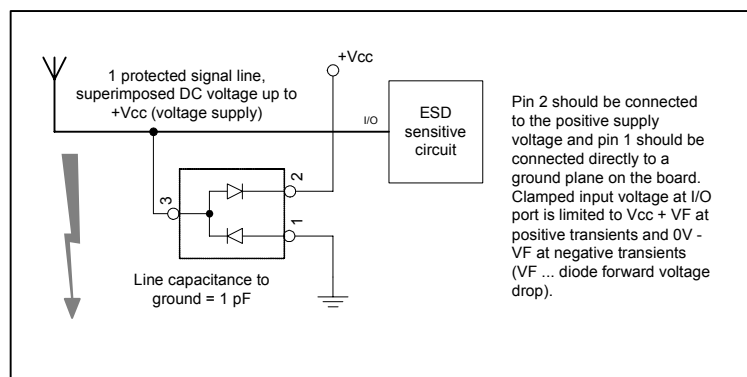
1. Application example ESD1P0RFW

1 channel, anti-parallel configuration



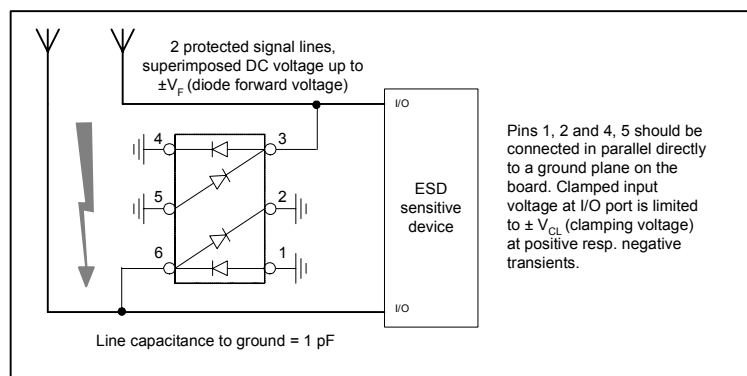
2. Application example ESD1P0RFW

1 channel, rail-to-rail configuration



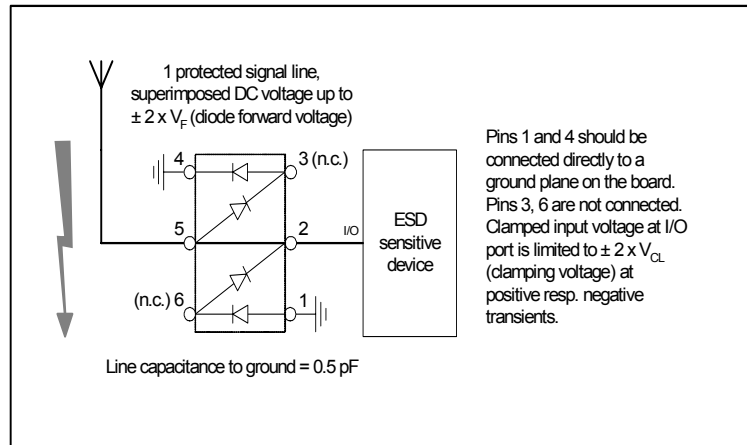
3. Application example ESD1P0RFS

2 channels, anti-parallel configuration

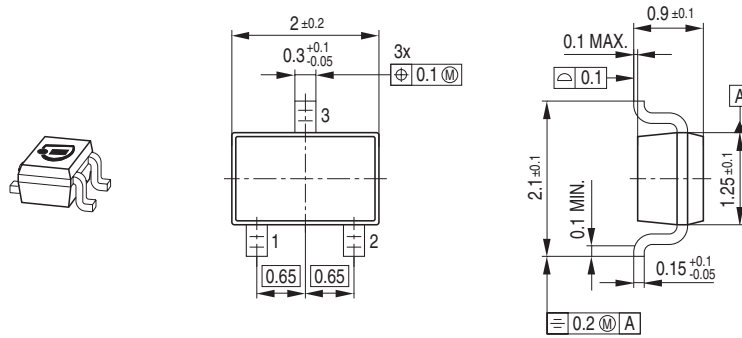


4. Application example ESD1P0RFS

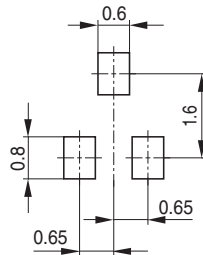
1 channel, low capacitance anti-parallel configuration



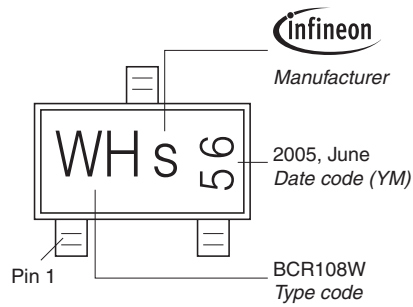
Package Outline



Foot Print

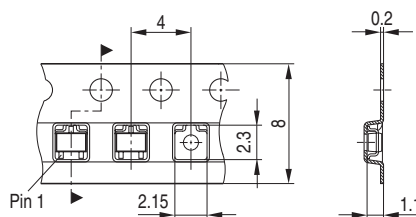


Marking Layout (Example)

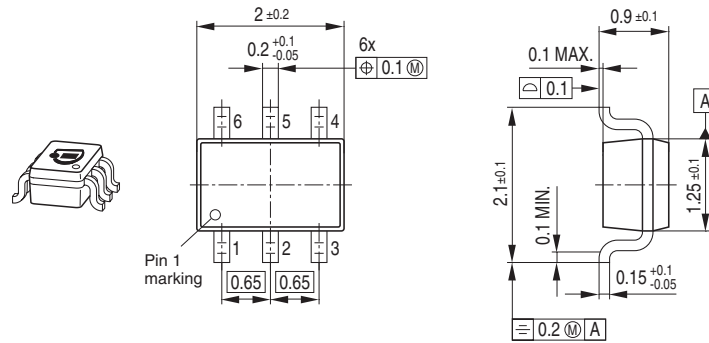


Standard Packing

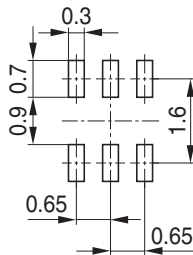
Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



Package Outline

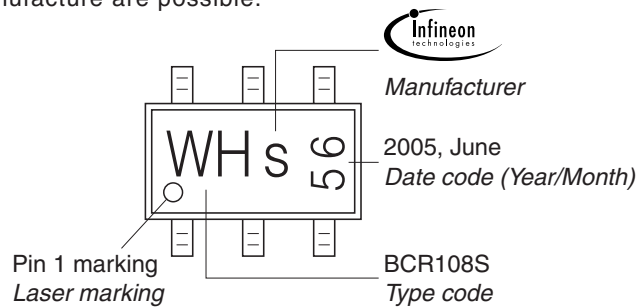


Foot Print



Marking Layout (Example)

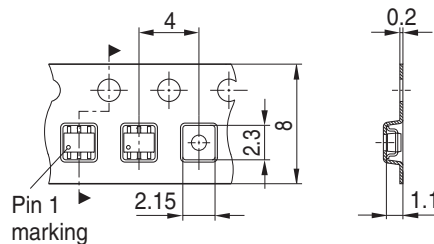
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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